



## Challenges and Directions Forward for Dealing with the Complexity of Future Smart Cyber-Physical Systems

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### Message from the Guest Editors

Dear Colleagues,

A key aspect of Cyber-Physical Systems (CPS) is their potential for integrating information technologies, operational technologies (in terms of embedded systems and control systems), and physical systems, to form new or improved functionalities. CPS, thus, draws upon advances in many areas.

In embarking towards CPS with such unprecedented capabilities it becomes essential to improve our understanding of CPS complexity and how we can deal with it. Complexity has many facets including complexity of the CPS itself, of the environments in which the CPS acts, and in terms of the organizations and supporting tools that develop, operate and maintain CPS.

The primary objective of this Special Issue is to provide a forum for researchers and practitioners to exchange their latest achievements and to identify critical issues, challenges, opportunities and future directions for how to deal with the complexity of future CPS. Welcome to contribute to this excellent project.

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## Message from the Editor-in-Chief

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